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## FACSIMILE COVER SHEET

**TO: Examiner James Mitchell , Art Unit 2827**

**Company: Assistant Commissioner for Patents**  
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**FROM: Joan N. Williams, Reg. No. 52,364/amm**

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*Patents, Trademarks and Related Matters*

**Killworth, Gottman, Hagan & Schaeff, L.L.P.**

One Dayton Centre  
One South Main Street, Suite 500  
Dayton, Ohio 45402-2023

937.223.2050  
Fax | 937.223.0724  
E-mail | [kghs@kghs.com](mailto:kghs@kghs.com)  
[www.KGH5.com](http://www.KGH5.com)

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**Remarks:**

**U.S. Patent Application Serial No. 09/804,051**

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## IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

## Application of

Applicant : Akram et al. ✓  
Serial No. : 09/804,051 ✓  
Filed : March 12, 2001  
Title : MULTIPLE DIE PACKAGE  
Docket No. : MIO 0069 PA  
Examiner : James Mitchell  
Art Unit : 2827  
Confirm. No. : 7513

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*Joan N. Williams*  
Joan N. Williams Reg. No. 52,364

Assistant Commissioner for Patents  
Washington, D.C. 20231

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AMENDMENT

This paper is being filed in response to the Office Action mailed August 1, 2002.  
Reconsideration is respectfully requested in light of the amendments and remarks below.

IN THE CLAIMS

The entire set of presently pending claims is reproduced below for the convenience of the Examiner. Amended claims are indicated as such in the parenthetical following the claim number. Further, enclosed herewith is Appendix A titled "Version With Markings To Show Changes Made" which corresponds to the amendments to the claims made herein.

Please amend claims 1, 3, 5, 10, 12, 14, 20-22, and 24.

1. (Amended) A multiple die semiconductor assembly comprising:
- a first semiconductor die defining a first active surface, said first active surface including at least one conductive bond pad;
  - a second semiconductor die defining a second active surface, said second active surface including at least one conductive bond pad; and
  - a single intermediate substrate positioned between said first semiconductor die and said second semiconductor die such that a first surface of said intermediate substrate faces said first